

SOT879-1

plastic low profile ball grid array package; 196 balls; body 15 x 15 x 1 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LPGA196
Package type industry code	LPGA196
Package style descriptive code	LPGA (low profile ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-192
Mounting method type	S (surface mount)
Issue date	19-4-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	14.8	-	15	15.2	mm
E	package width	14.8	-	15	15.2	mm
A	seated height	[tbd]	-	1.55	1.55	mm
A ₂	package height	0.9	-	1	1.1	mm
n ₂	actual quantity of termination	-	-	196	-	



2. Package outline

LPGA196: plastic low profile ball grid array package; 196 balls; body 15 x 15 x 1 mm SOT879-1

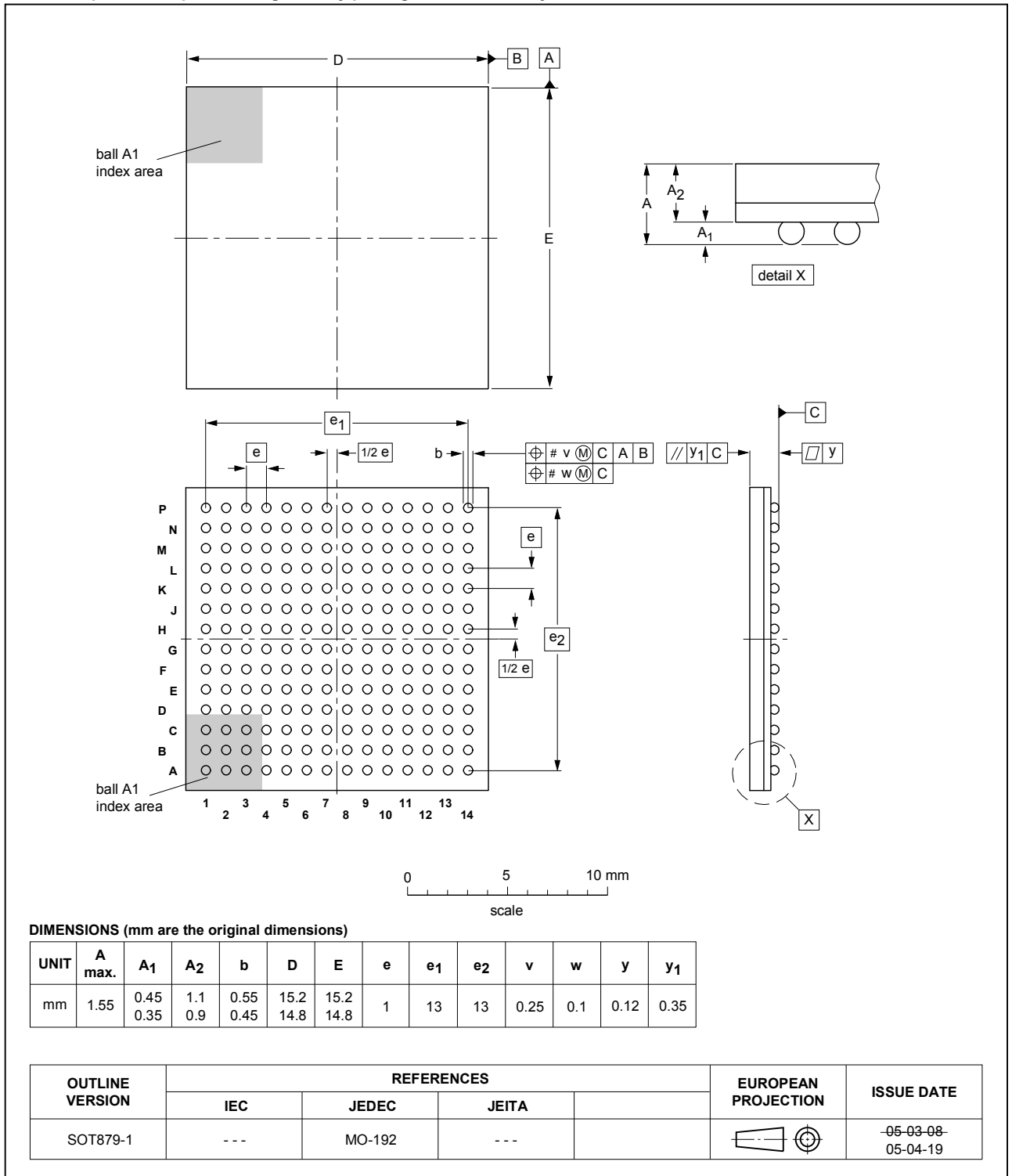


Fig. 1. Package outline LPGA196 (SOT879-1)

3. Soldering

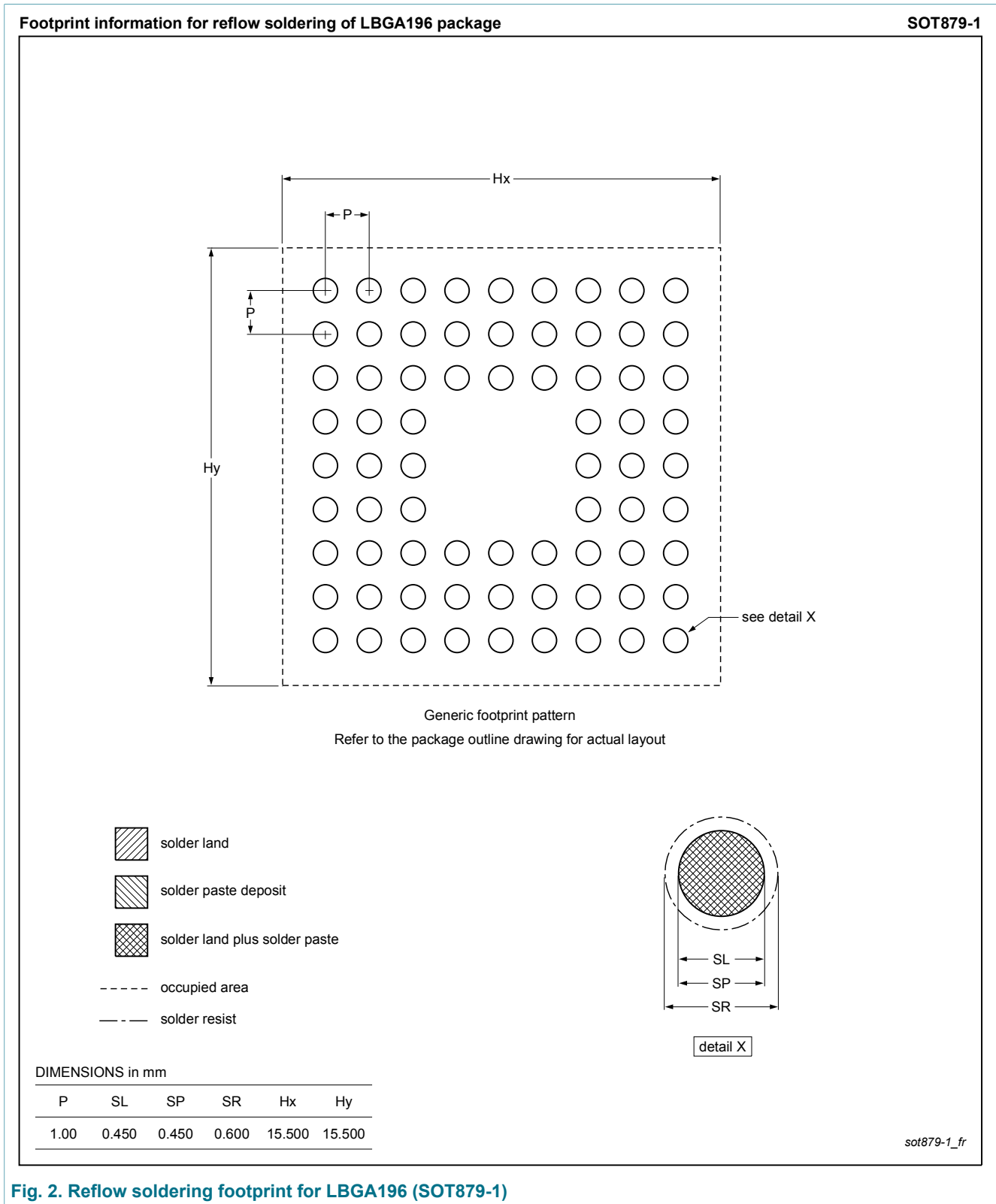


Fig. 2. Reflow soldering footprint for LBG196 (SOT879-1)

4. Legal information

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